

DDR4 miniDIMM Sockets

Vertical, SMT, with and without center fork lock



Achieve ultimate PCB space-savings in enterprise computing and networking memory applications with the industry's first compact DDR4 miniDIMM Socket

Features and Benefits

Small form factor design (approximately 2/3 smaller than standard DDR4 DIMM sockets)	Maximizes space savings for tight-spaced memory applications
Metal grips on housing towers (patent pending)	Reduce shock or vibration to mounted memory module during transit
Latches that can withstand at least 25 mating cycles	Offer high durability in mission-critical applications
Profiled contacts with high normal force	Provides excellent contact reliability
Designed to withstand two reflow cycles	Ensures optimal performance under heat
Pick-and-place cap option	For automated processing



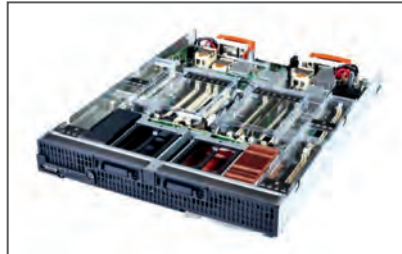
Applications

Data/Computing

- High-end computing
- Personal computers
- RAID / Storage

Telecommunications/Networking

- Infrastructure
- Networking



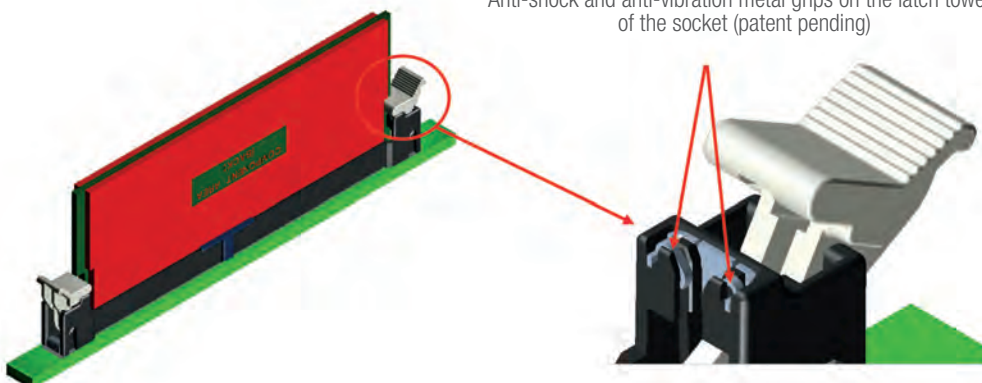
High Memory-Density Servers



Data Centers

Product Features

Anti-shock and anti-vibration metal grips on the latch towers of the socket (patent pending)



Latch tower design of the DDR4 miniDIMM Socket

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Specifications

Reference Information

Packaging: Tray
 Use With: JEDEC MO-314 memory modules
 Designed In: Millimeter
 RoHS: Yes
 Halogen Free: No
 Glow Wire Compliant: No

Electrical

Voltage (max.): 29V AC (RMS)/DC
 Current (max.): 0.75A per pin
 Low Level Contact Resistance (max.): 20 milliohms initial
 Dielectric Withstanding Voltage: 500V AC
 Insulation Resistance (min.): 1 Megohm

Mechanical

Module Insertion Force (max., with latches): 150.0N
 Module Rip-out Force (min.): 3.6kgf
 Module Unmating Force: 2.02kgf (14.4gf per pair pin)
 Terminal Retention Force (min.):
 300gf (per pin); 10.0N (per fork lock)
 Latch Actuation Force (max.): 35.0N per latch
 Durability: 25 cycles

Physical

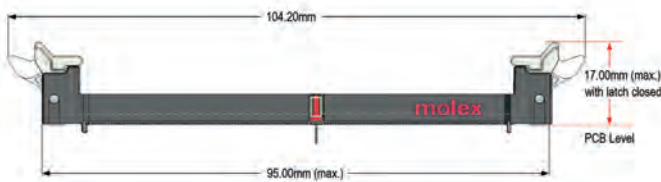
Pitch: 0.50mm
 Housing: LCP, glass-filled, black, UL94V-0
 Latch: Polyamide, glass-filled, off-white, UL94V-0
 Terminal: Copper Alloy
 Plating:
 Contact: 0.76µm Gold (Au) over 1.27µm Nickel;
 Solderails: 2.54µm Tin (Sn) over 1.27µm Nickel (Ni);
 PCB Tabs: 2.54µm Tin (Sn) over 1.27µm Nickel (Ni)
 Operating Temperature: -55 to +85°C

Ordering Information

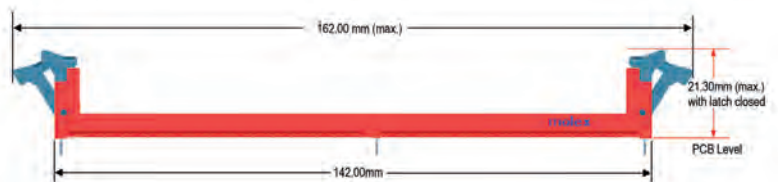
Series No.	Style	Termination	Product Specification
151105	miniDIMM	SMT	PS-151105-0001

DDR4 DIMM Connector Dimensions - miniDIMM Versus Standard Version

(Remark: Illustrations Not Drawn To Scale)

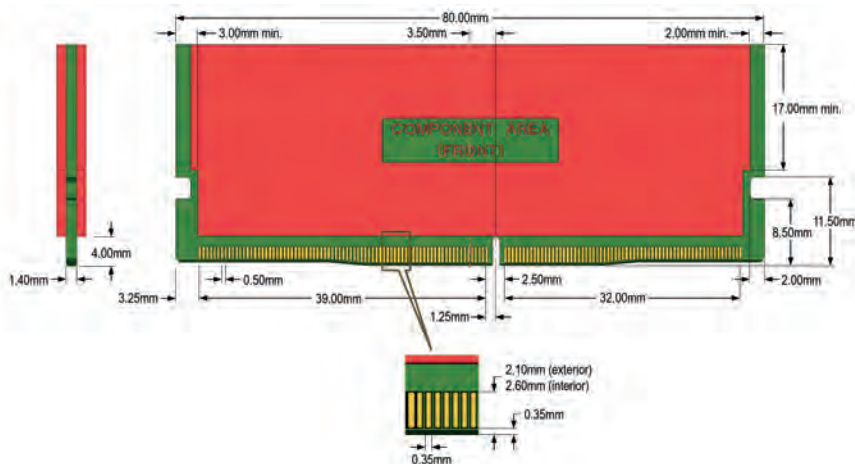


More compact dimensions of the DDR4 miniDIMM Socket



Dimensions of a Standard DDR4 DIMM Socket

DDR4 miniDIMM Module PCB Dimensions



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